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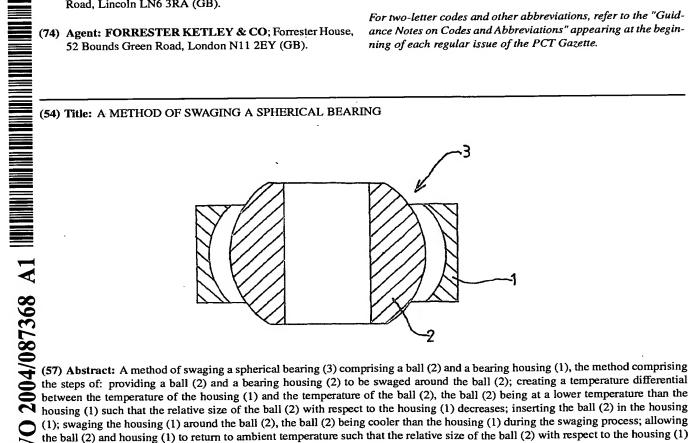
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For two-letter codes and other abbreviations, refer to the "Guid-



(1); swaging the housing (1) around the ball (2), the ball (2) being cooler than the housing (1) during the swaging process; allowing the ball (2) and housing (1) to return to ambient temperature such that the relative size of the ball (2) with respect to the housing (1) increases.

